

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Da CHENG</td> <td>10/24/2011</td> </tr> <tr> <td>Chih-Wei LIN</td> <td>10/24/2011</td> </tr> <tr> <td>Kuei-Wei HUANG</td> <td>10/24/2011</td> </tr> <tr> <td>Yu-Peng TSAI</td> <td>10/24/2011</td> </tr> <tr> <td>Chun-Cheng LIN</td> <td>10/25/2011</td> </tr> <tr> <td>Chung-Shi LIU</td> <td>10/25/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Da CHENG	10/24/2011	Chih-Wei LIN	10/24/2011	Kuei-Wei HUANG	10/24/2011	Yu-Peng TSAI	10/24/2011	Chun-Cheng LIN	10/25/2011	Chung-Shi LIU	10/25/2011
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RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.														
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park														
City:	Hsinchu														
State/Country:	TAIWAN														
Postal Code:	300														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13277575</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13277575										
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Application Number:	13277575														
CORRESPONDENCE DATA															
Fax Number:	(703)518-5499														
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OP \$40.00 13277575

NAME OF SUBMITTER:

Randy A. Noranbrock

Total Attachments: 2

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Ming-Da CHENG
- 2) Chih-Wei LIN
- 3) Kuei-Wei HUANG
- 4) Yu-Peng TSAI
- 5) Chun-Cheng LIN
- 6) Chung-Shi LIU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR PACKAGE

(a) for which an application for United States Letters Patent was filed on 2011-10-20, and identified by United States Patent Application No. 13/277,575; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Ming-Da Cheng
Name: Ming-Da CHENG

2011/10/24
Date:

2) Chih-Wei Lin
Name: Chih-Wei LIN

2011/10/24
Date:

3) Kuei-Wei Huang
Name: Kuei-Wei HUANG

2011/10/24
Date:

4) Yu-Peng Tsai
Name: Yu-Peng TSAI

2011/10/24
Date:

5) Chun-Cheng Lin
Name: Chun-Cheng LIN

2011/10/25
Date:

6) Chung-Shi Liu
Name: Chung-Shi LIU

2011/10/25
Date: